

SPECIFICATION

MODEL : SPHWWTS8N105EBW0H3



[Rank : Vf (E5, K7),
CIE (W1, W2, W3, W4, W5, W6, W7, W8, W9, WA,
WB, WC, WD, WE, WF, WG),
Im (H1, M1)]

HIGH POWER LED - SUNNIX8

CUSTOMER		
CHECKED	CHECKED	APPROVED

SAMSUNG LED			
DRAWN	CHECKED(Sales)	CHECKED(Quality)	APPROVED

SAMSUNG LED CO.,LTD.

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1. Product Outline

1) Features

- Plastic Molded Lead Frame Type : 6.0 mm(L), 7.0 mm(W), 1.2 mm(T)
- Beam View Angle($\Delta\theta$)* : 120 °
- High Power / Brightness Chip & Long Time Reliability

2) Applications

- General Lighting, Indoor Illumination, Refrigerator lighting etc.

※ View Angle describes the spatial intensity distribution and is the difference between the angles corresponding to 50% of the maximum intensity.

2. Absolute Maximum Rating

- Operation Forward Current⁽¹⁾ 700 mA
- Peak Pulsed Forward Current 800 mA
(Duty 1/10 and Pulse Width 10 msec)
- Reverse Current⁽²⁾ 20 mA
- Thermal Resistance ($R_{th\ j-s}$) \cong 5 °C/W
- Operating Temperature Range (T_{OPR}) -40 °C ~ 85 °C
- Storage Temperature Range (T_{STG}) -40 °C ~ 110 °C
- LED Junction Temperature (T_j) 125 °C

(1) Refer to derating curve in the page 6.

(2) Does not operate in the reverse direction.

3. Characteristics

1) Electrical properties ($T_a = 25\text{ °C}$)

Parameter	Symbol	Condition	Rank	Min.	Typ.	Max.	Unit
Reverse Voltage	V_R	$I_R = 10\text{ mA}$	-	0.5	0.8	2.0	V
Forward Voltage	V_F	$I_F = 350\text{ mA}$	EB	E5	2.90	3.15	
				K7	3.15	3.50	

2) Color Rendering Index ($T_a = 25\text{ °C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Color Rendering	R_a	$I_F = 350\text{ mA}$	80	83	-	-

3) Chromaticity Coordinates ($T_a = 25 \text{ }^\circ\text{C}$)

Item	Condition	Rank	x				y				
Chromaticity Coordinate (*)	$I_F=350\text{mA}$	W0	W1	0.4373	0.4428	0.4475	0.4418	0.3893	0.3906	0.3994	0.3981
			W2	0.4428	0.4483	0.4532	0.4475	0.3906	0.3919	0.4008	0.3994
			W3	0.4483	0.4538	0.4589	0.4532	0.3919	0.3931	0.4021	0.4008
			W4	0.4538	0.4593	0.4646	0.4589	0.3931	0.3944	0.4034	0.4021
			W5	0.4418	0.4475	0.4523	0.4465	0.3981	0.3994	0.4085	0.4071
			W6	0.4475	0.4532	0.4582	0.4523	0.3994	0.4008	0.4099	0.4085
			W7	0.4532	0.4589	0.4641	0.4582	0.4008	0.4021	0.4112	0.4099
			W8	0.4589	0.4646	0.47	0.4641	0.4021	0.4034	0.4126	0.4112
			W9	0.4465	0.4523	0.4573	0.4513	0.4071	0.4085	0.4178	0.4164
			WA	0.4523	0.4582	0.4634	0.4573	0.4085	0.4099	0.4193	0.4178
			WB	0.4582	0.4641	0.4695	0.4634	0.4099	0.4112	0.4207	0.4193
			WC	0.4641	0.47	0.4756	0.4695	0.4112	0.4126	0.4221	0.4207
			WD	0.4513	0.4573	0.4624	0.4562	0.4164	0.4178	0.4274	0.426
			WE	0.4573	0.4634	0.4687	0.4624	0.4178	0.4193	0.4289	0.4272
			WF	0.4634	0.4695	0.475	0.4687	0.4193	0.4207	0.4304	0.4289
WG	0.4695	0.4756	0.4813	0.475	0.4207	0.4221	0.4319	0.4304			

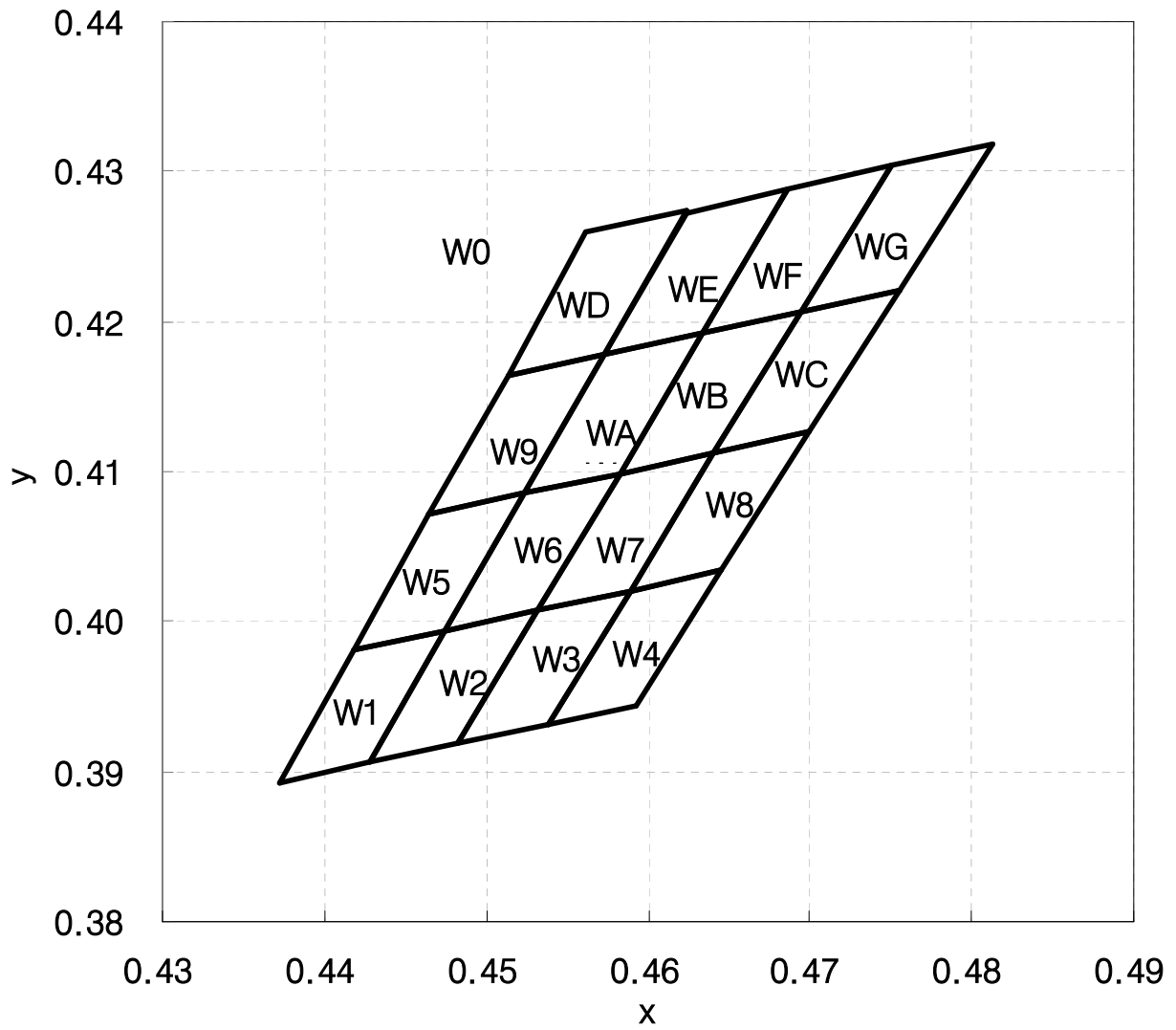
4) Luminous Flux ($T_a = 25 \text{ }^\circ\text{C}$)

Parameter	Symbol	Condition	Rank	Min.	Typ.	Max.	Unit
Luminous Flux	Φ_V	$I_F = 350 \text{ mA}$	H3	H1	90	105	lm
				M1	105	-	

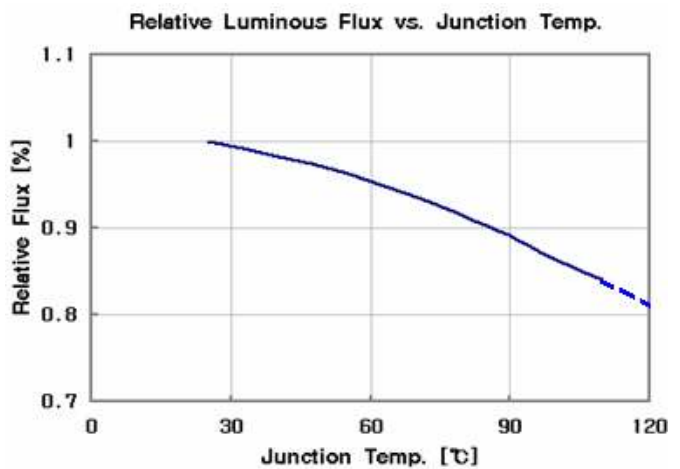
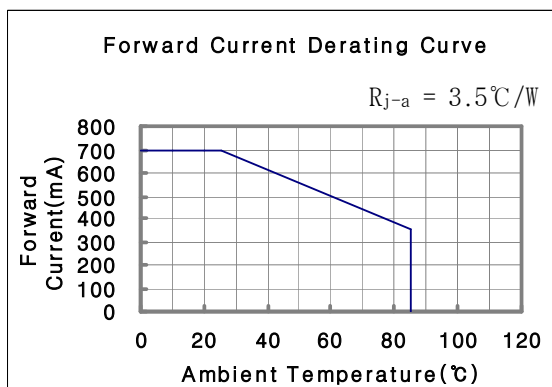
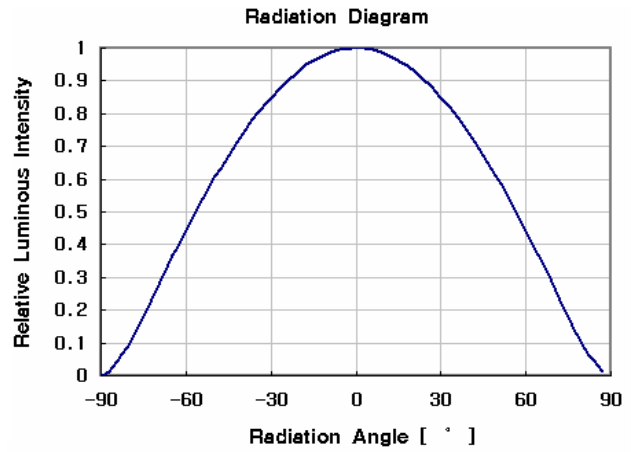
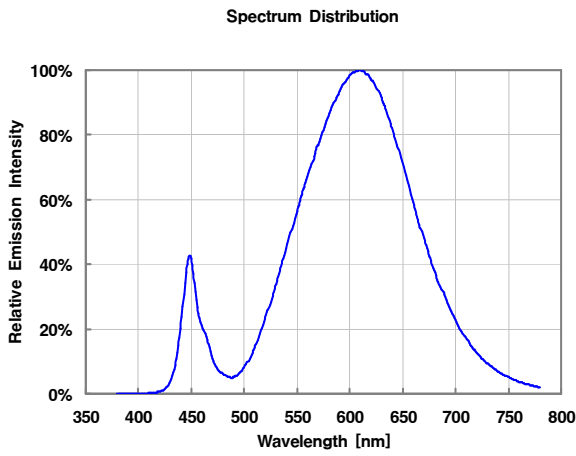
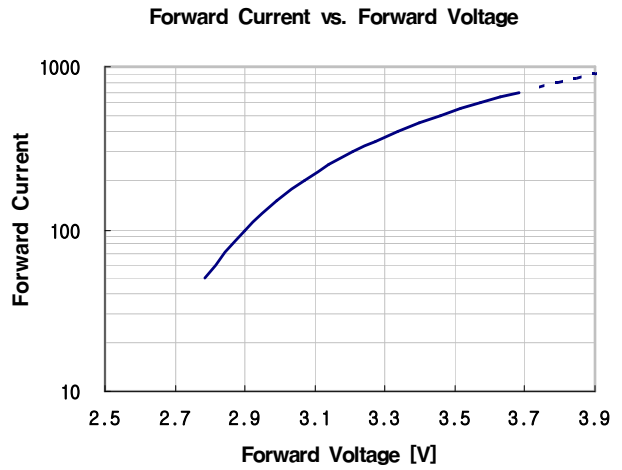
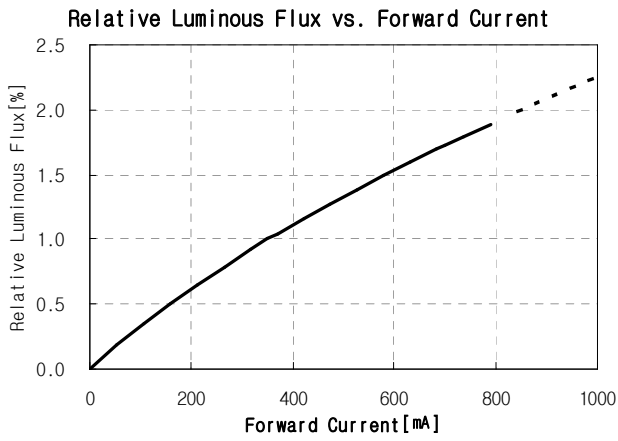
※ Tolerance : $V_F : \pm 0.1$, $\Phi_V : \pm 7 \%$, $CCx \ CCy : \pm 0.02$, $R_a : \pm 5.0$

※ Luminous Intensity measuring equipment : CAS140CT

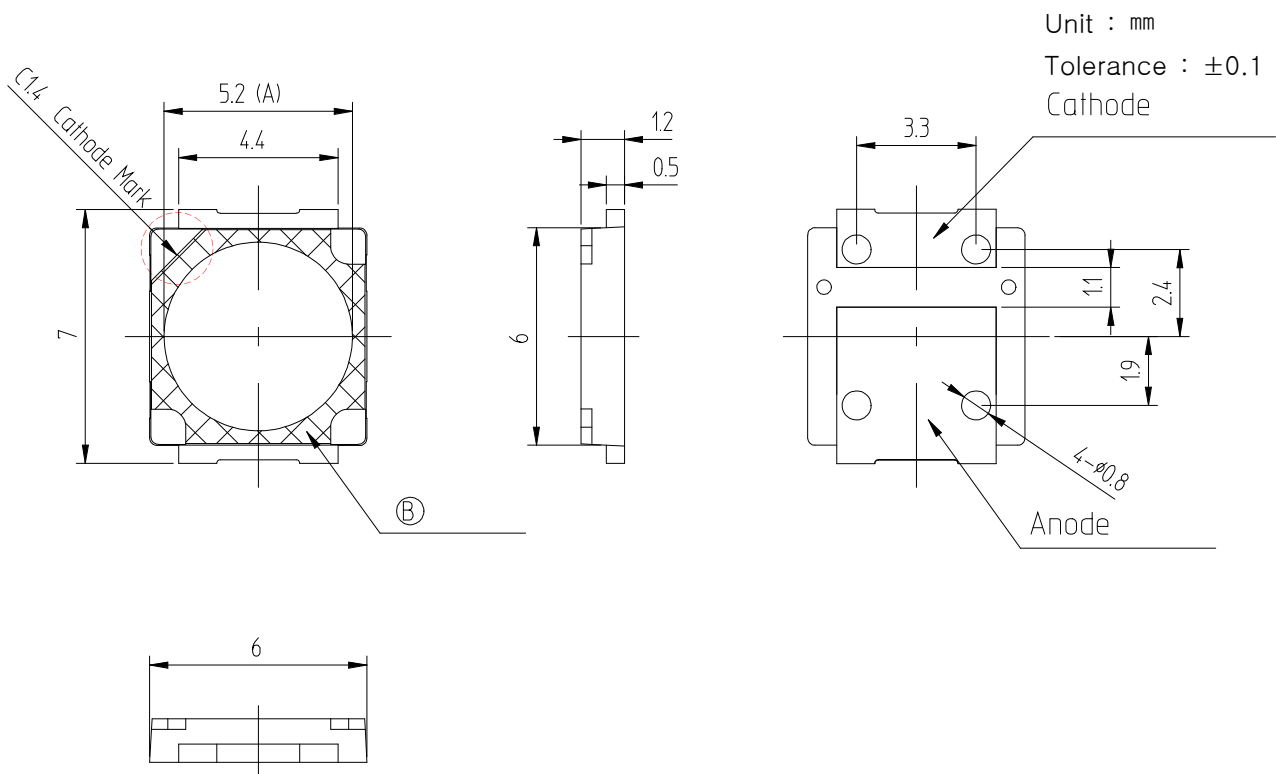
4. Chromaticity Diagram



5. Typical Characteristic Graphs



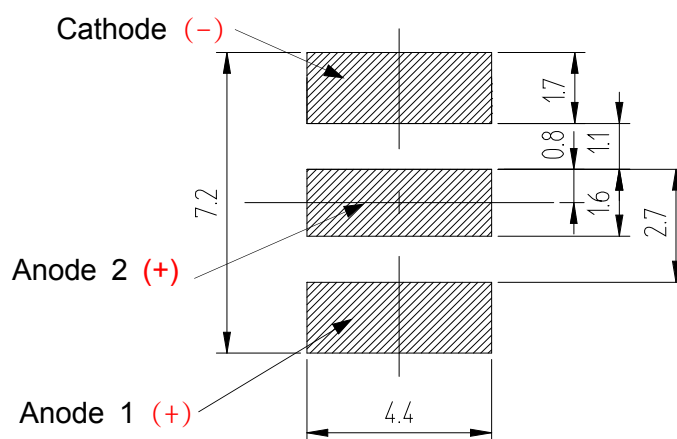
6. Outline Drawing and Dimension



Pick and Place

- Do not place pressure on the encapsulating resin ("A")
It is recommended to use a pick&place nozzle with inside diameter at 5.2mm
- The maximum compressing force is 15N on the polymer ("B")

Solder Pattern for Surface Mount



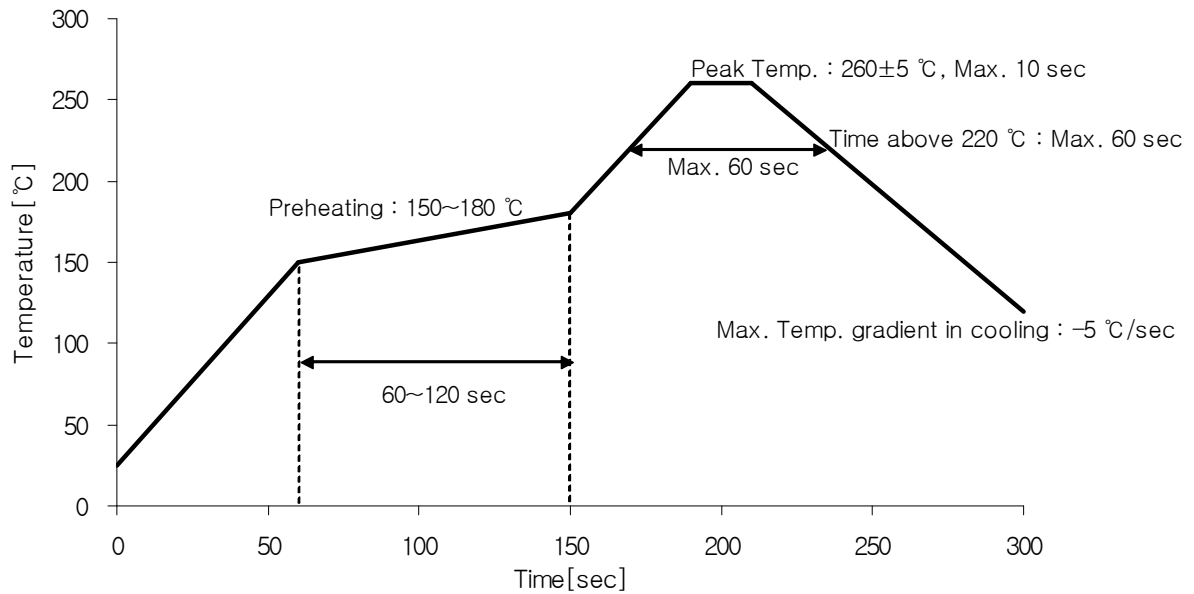
Remarks

- * Make sure that Anode 2 is electrically connected to the Anode 1.
- * Anode 2 is to be soldered, If not, use the heat conductive adhesive.
- * This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).

7. Solder Conditions

1) Reflow Conditions (Pb-Free)

Reflow Frequency : 2 time max.

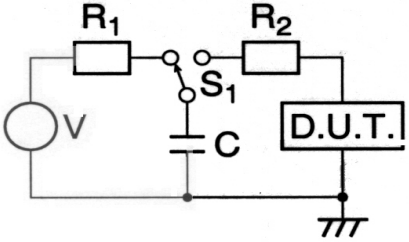


2) For Manual Soldering

Not more than 5 seconds @Max. 300 °C, under soldering iron.

8. Reliability Test Items and Conditions

1) Test Items

Test Items	Test Conditions	Test Hours/Cycles
Room Temperature life test	25 °C, $I_F = \text{Max DC}^*$	1,000 h
High Temperature humidity life test	85 °C, 85 % RH, $I_F = \text{Max DC}^*$	1,000 h
High Temperature life test	85 °C, $I_F = \text{Max DC}^*$	1,000 h
Low Temperature life test	-40 °C, $I_F = \text{Max DC}^*$	1,000 h
High Temperature Storage	110 °C	1,000 h
Low Temperature Storage	-40 °C	1,000 h
Thermal Shock	-40 / 120 °C, each 30 min	200 cycles
Temperature humidity Cycle On/Off test	-40 / 85 °C, each 20 min, 100 min transfer Power On/off each 5 min, DC 350 mA	100 cycles
Reflow (Pb-Free)	Peak 260±5 °C for 10 sec	3 times
ESD(HBM)	 <p>R1 : 10 MΩ , R2 : 1.5 kΩ , C : 100 pF</p>	3 times (± 5 kV)

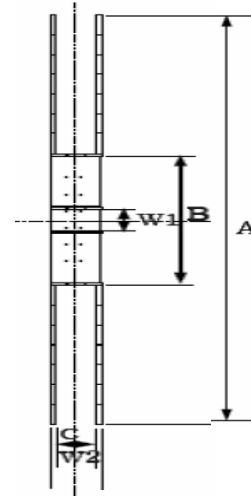
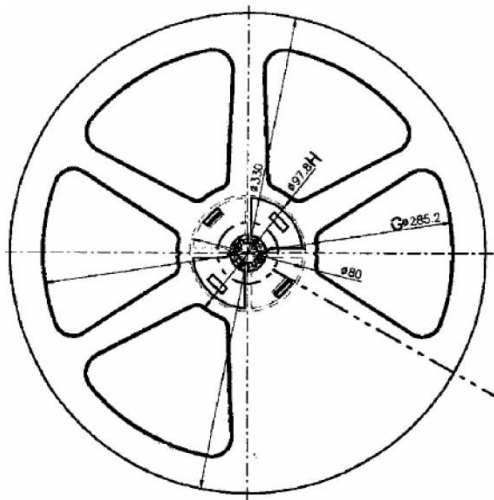
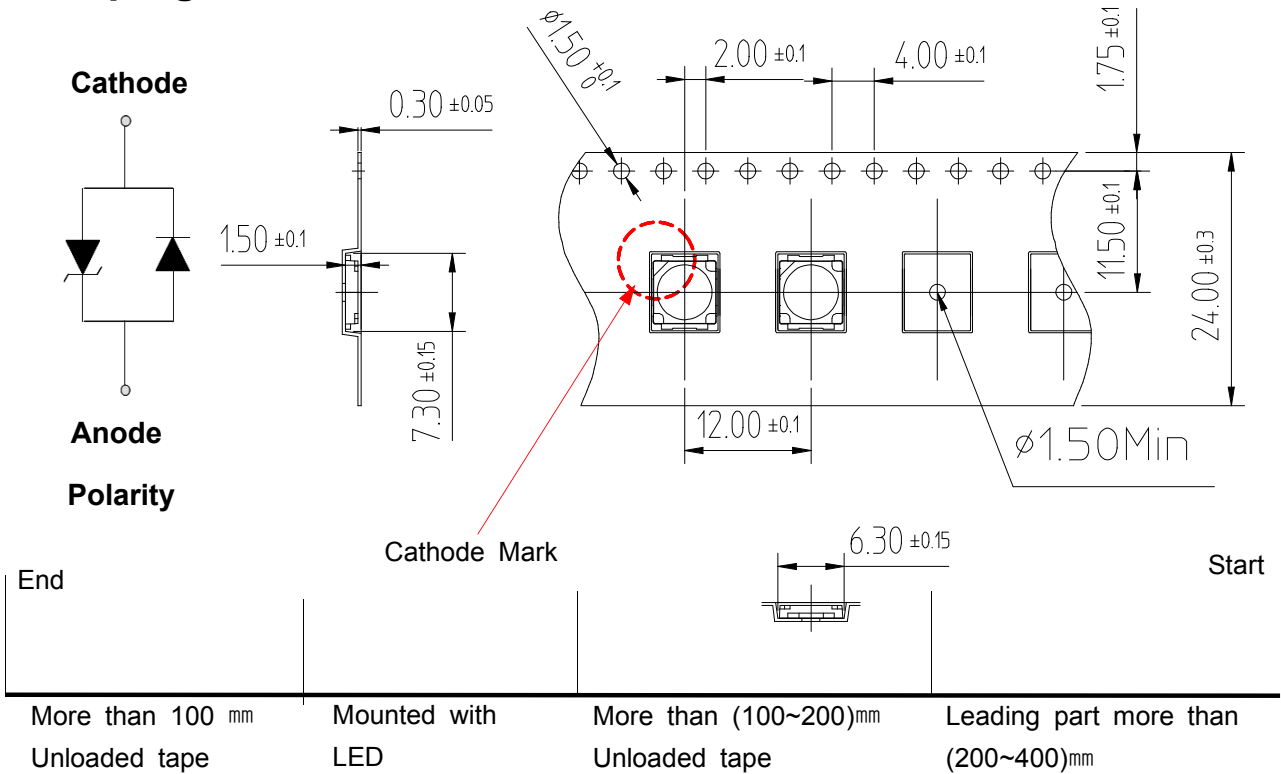
* Max. DC current is depending on maximum current derating curve.

2) Criteria for Judging the Damage

Item	Symbol	Test Condition	Limit	
			Min	Max
Forward Voltage	V_F	$I_F = 350 \text{ mA}$	-	U.S.L.*1.1
Luminous Flux	Φ_V	$I_F = 350 \text{ mA}$	L.S.L.*0.7	-

* U.S.L : Upper Standard Level, L.S.L : Lower Standard Level

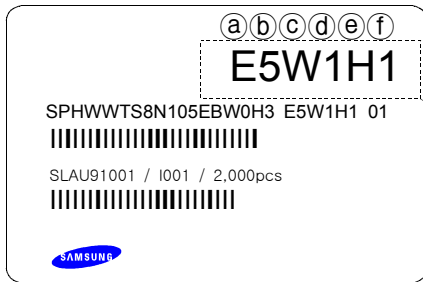
9. Taping Dimension



Symbol	A	B	C	W1	W2
Dimension(mm)	330 ± 1	80 ± 1	25 ± 0.5	13 ± 0.3	29.5 ± 1

- (1) Quantity : 2,000 Pcs / 13" Reel.
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches is less than ±0.2 mm
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at 10 °C angle to be the carrier tape.
- (4) Packaging : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

10. Label Structure

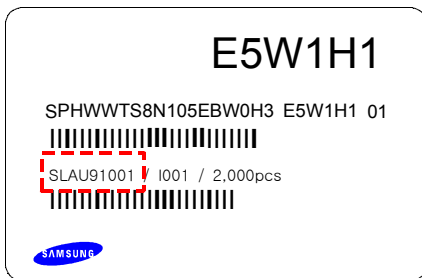


Rank Code

- Ⓐ Ⓑ : VF Rank (refer to page 3)
- Ⓒ Ⓓ : Chromaticity Coordinate Rank, CIE (refer to page 4)
- Ⓔ Ⓕ : Luminous Flux (refer to page 4)

11. Lot Number

The Lot number is composed of the following characters

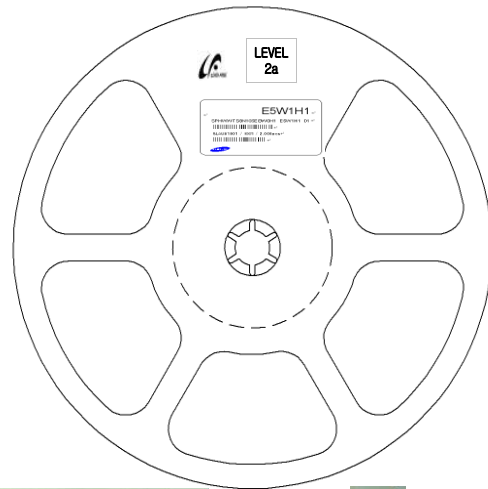
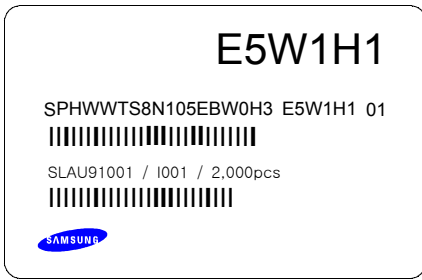


● ◎ ◇ ◆ □ ■ △ △ △ / | ▲ ▲ ▲ / 2000PCS

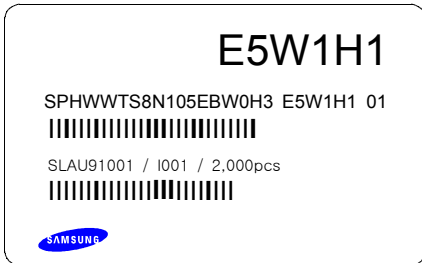
- : Production Site (S:SAMSUNG LED, G:Gosin China)
- ◎ : L (LED)
- ◇ : Product State (A:Normality, B:Bulk, C:First Production, R:Reproduction, S:Sample)
- ◆ : Year (S:2008, T:2009, U:2010...)
- : Month (1 ~ 9, A, B)
- : Day (1 ~ 9, A, B ~ V)
- △ : SAMSUNG LED Product Number (1 ~ 999)
- ▲ : Reel Number (1 ~ 999)

12. Reel Packing Structure

1) Reel



2) Aluminum Bag



Humidity Indicator Card Silica gel

CAUTION LEVEL 2a
This bag contains MOISTURE SENSITIVE DEVICES

- Shelf life in sealed bag: 12 months at $+40^{\circ}\text{C}$ and $+90\%$ relative humidity (RH)
- Peak package body temperature: 240°C
- After this bag is opened, devices that will be subjected to yellow sulfur or other high temperature processes must be:
 - Measured within 672 hours at factory conditions of equal to or less than 30°C / 60% RH, or
 - Stored at <math>< 10\%</math> RH
- Devices require baking, before mounting, if:
 - a Humidity Indicator Card is > 90% when read at $23 \pm 5^{\circ}\text{C}$, or
 - It is not met.
- If baking is required, devices must be baked for 1 hour at $60 \pm 5^{\circ}\text{C}$.
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedures.
Bag seal date date:
(If blank, see code label)
Note: Level and body temperature by IPC/JEDEC J-STD-020

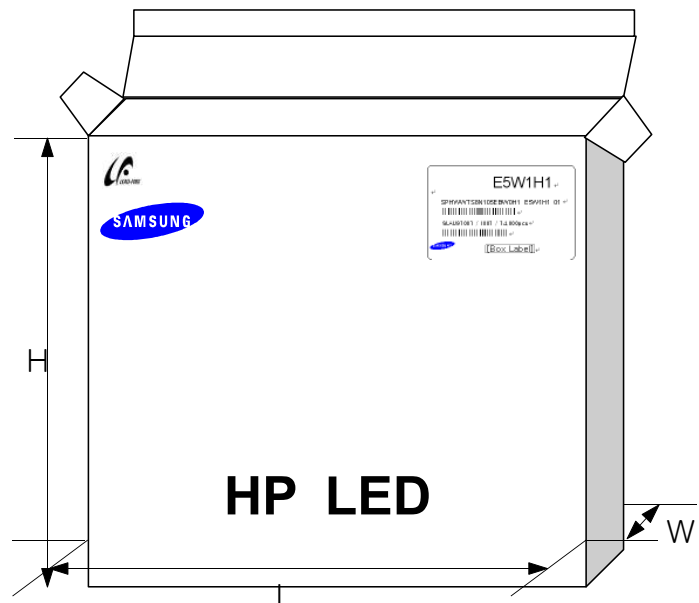
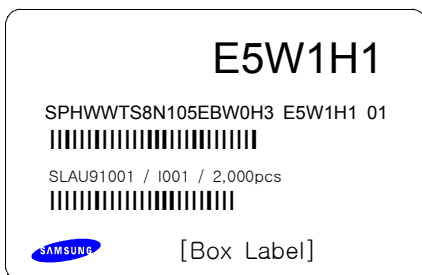
주의 사항
이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하기 위하여 제작되었습니다. 개봉 후에는 즉시 출하 작업을 실시하는 것을 권장합니다.
습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용하지 않는 제품은 본 백에 넣어 보관 하시기 바랍니다. 사용하지 않는 제품을 본 백에 넣을 때는 반드시 동봉된 드라이퍼 팩과 함께 넣고 지퍼부분을 완전히 밀봉하여 주시기 바랍니다.

Important
This AI Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the AI Zipper Bag. To repack unused products, please ensure the zip-lock is completely sealed with the dry pack left inside.

3) Inner Box

Material : Paper(SW3B(B))

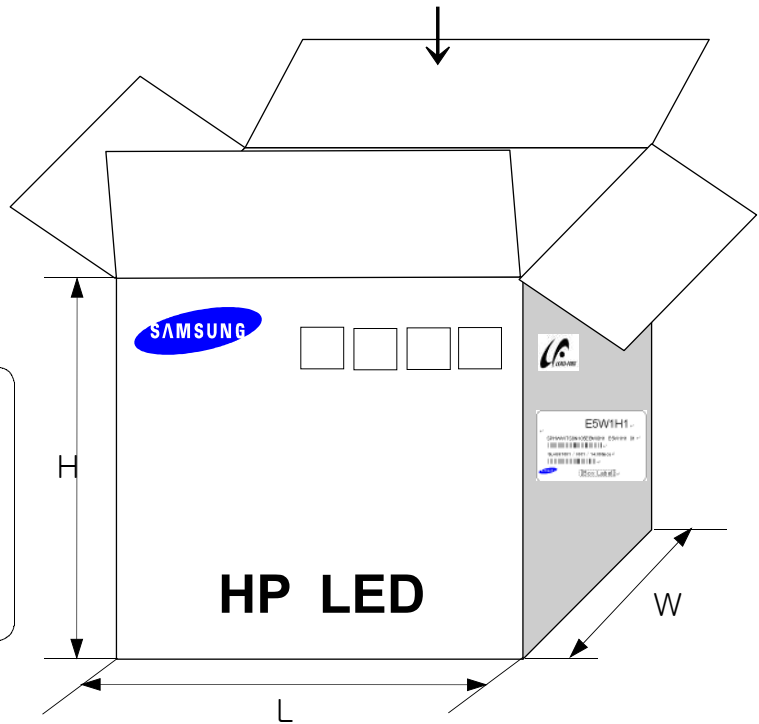
TYPE	SIZE(mm)		
	L	W	H
13inch	335	45	335




4) Carton Box

Material : Paper(SW3B(B))

TYPE	SIZE(mm)		
	L	W	H
13inch	350	350	350



13. Aluminum Vinyl Bag



CAUTION

This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL
2a

1. Shelf life in sealed bag: 12 months at 40°C and <math><90\%</math> relative humidity (RH)
2. Peak package body temperature: 240°C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C / 60% RH, or
 - b. Stored at <math><10\%</math> RH
4. Devices require bake, before mounting, if:
 - a. Humidity Indicator Card is > 65% when read at $23\pm 5^{\circ}\text{C}$, or
 - b. 2a is not met.
5. If baking is required, devices must be baked for 1 hours at $60\pm 5^{\circ}\text{C}$


Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure,

Bag seal due date: _____
(if blank, see code label)



Note: Level and body temperature by IPC/JEDEC J-STD-020

E5W1H1

SPHWWMTS8N105EBW0H3 E5W1H1 01



SLAU91001 / 1001 / 2,000 pcs



주의 사항

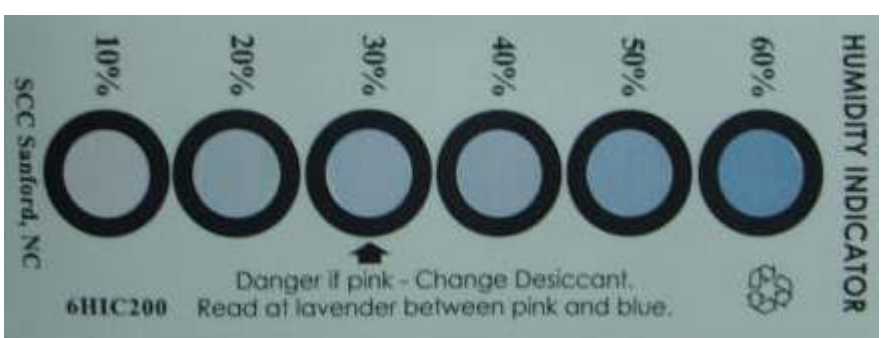
이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 실시하는 것을 권장합니다.

습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용하지 않는 자재는 본 팩에 넣어 보관 하시기 바랍니다. 사용하지 않는 자재를 본 팩에 넣을 때는 반드시 동봉된 드라이 팩과 함께 넣고 지퍼부분을 완전하게 밀봉하여 주시기 바랍니다.

Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

Silica gel & Humidity Indicator Card in Aluminum Vinyl Bag



14. Precaution for Use

- 1) For over-current-proof function, customers are recommended to apply resistors to prevent sudden change of the current caused by slight shift of the voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA is recommended to use.
- 3) When the LEDs illuminate, operating current should be decided after considering the ambient maximum temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for 3 months or more after being shipped from SAMSUNG LED, they should be packed by a sealed container with nitrogen gas injected. (Shelf life of sealed bags : 12 months, temp. 0~40℃, 20~70%RH)
- 5) After storage bag is open, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 168 hours (7days) at an assembly line with a condition of no more than 30℃/60%RH,
 - b. Stored at <10% RH.
- 6) Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60% at 23±5℃.
- 8) Devices must be baked for 24hours at 65±5℃, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices.

Damaged LEDs may show some unusual characteristics such as increase in leak current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.

- 10) When handling LED with tweezers, the LED Should only be held by the polymer body, not by the encapsulant or LENS.

- 11) The use of appropriate nozzle for the LED recommended. For the recommended nozzle size, refer to the figure at the below.
Inner diameter of nozzle $\geq \Phi 6.1\text{mm}$

- 12) Do not stack assembled PCBs together. Since silicone is a soft material, abrasion between two PCB assembled with silicone encapsulated LED might cause catastrophic failure of the LEDs due to damage to encapsulant and wire and LED detachment.

15. Hazard Substance Analysis



Test Report No. F690501/LF-CTSAYAA10-41879

Issued Date: December 22, 2010

Page 1 of 5

To: SAMSUNG LED CO.,LTD.
314, Maetan-dong
Yeongtong-gu
Suwon-city
GYEONGGI-DO 443-370
Korea

The following merchandise was submitted and identified by the client as :

SGS File No. : AYAA10-41879
Product Name : LED PKG
Item No./Part No. : Sunnix8 PKG(White)
Received Date : Dec 17, 2010
Test Period : Dec 20, 2010 to Dec 22, 2010
Test Performed : SGS Testing Korea tested the sample(s) selected by applicant with following results
Test Results : For further details, please refer to following page(s)
Comments : By the applicant's specific request, the sampling and testing was performed only for the part indicated in the photo without disassembly.

Timothy Jeon
Jinhee Kim
Cindy Park
Jerry Jung/ Testing Person

SGS Testing Korea Co. Ltd.

Jeff Jang / Chemical Lab Mgr

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Unless otherwise stated the results shown in this report refer only to the sample(s) tested and such sample(s) contained in 100 days only.

F052 Version3

SGS Testing Korea Co., Ltd.

322, The O valley, 555-0, Hoggae-dong, Dongan-gu, Anyang-si, Gyeonggi-do, Korea 431-000
t +82 (0)1 4508 000 f +82 (0)1 4500 050 <http://www.sgslab.co.kr> www.kr.sgs.com/greenlab

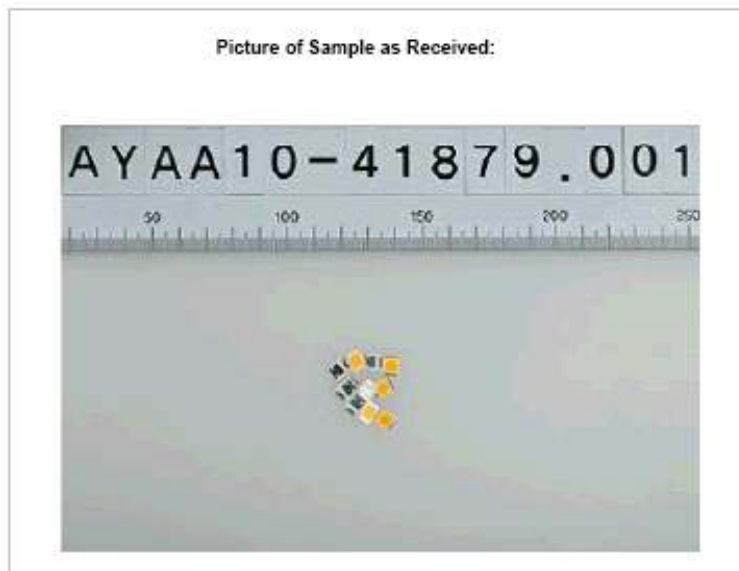
Member of the SGS Group (Société Générale de Surveillance)

Sample No. : AYAA10-41879.001
Sample Description : LED PKG
Item No./Part No. : Sunnix8 PKG(White)

Halogen Contents

Test Items	Unit	Test Method	MDL	Results
Bromine(Br)	mg/kg	BS EN 14582:2007 , IC	30	N.D.
Chlorine(Cl)	mg/kg	BS EN 14582:2007 , IC	30	N.D.

Picture of Sample as Received:



- NOTE:
- (1) N.D. = Not detected.(<MDL)
 - (2) mg/kg = ppm
 - (3) MDL = Method Detection Limit
 - (4) - = No regulation
 - (5) ** = Qualitative analysis (No Unit)
 - (6) * = Boiling-water-extraction:
 Negative = Absence of CrVI coating
 Positive = Presence of CrVI coating; the detected concentration in boiling-water-extraction solution is equal or greater than 0.02 mg/kg with 50 cm2 sample surface area.

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